



Integrated Device Technology, Inc.
6024 Silver Creek Valley Road
San Jose, CA 95138 USA

Manufacturing Bulletin

Subject: Product shipment in trays

Date: 9 Jul 2010

The purpose of this bulletin is to notify our customers that due to closure of IDT Singapore facility, all future product shipments in trays will be packed per existing IDT Penang facility procedure. There is no change to the tray dimensions and quantity per tray. This change in packing procedure will not impact the MOQ (Minimum Order Quantity) and FOI (Factory Order Increment).

This change in packing procedure does not impact the product Form/FIT/Function and provides better protection against damage during shipment. IDT Penang standard tray packing procedure is as follow:

- i) Maximum 4 full trays with units +1 cover tray per bundle**
- ii) 3+1 strap per bundle**
- iii) With end-cap (2 pieces per bundle)**

Please refer to attachment I for illustration of IDT Singapore versus IDT Penang tray packing procedure.

Yours sincerely,

A handwritten signature in black ink, appearing to read 'LS Koay', is written over a horizontal line.

**LS Koay
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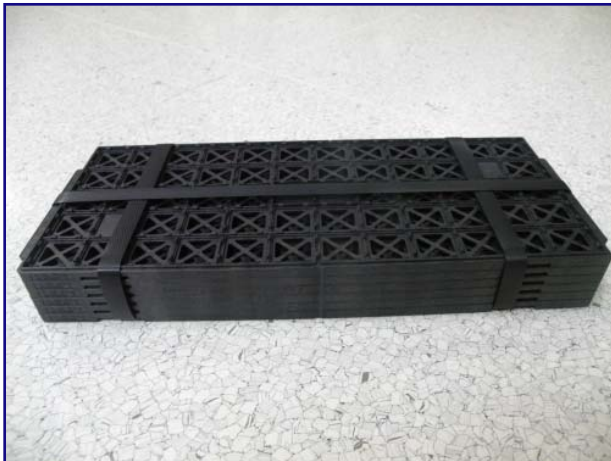
Manufacturing Bulletin **Attachment I**

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IDT Singapore Packing

- 5+1 per bundle.
- 2+1 strap per bundle.
- Without end-cap.



IDT Penang Packing

- 4+1 per bundle.
- 3+1 strap per bundle.
- With end-cap (2 pieces per bundle).

